INFORMATION DISCLOSURE CITATION IN AN APPLICATION				ATTY. DOCKET NO. 49959-118		SERIAL NO. 09/645,690				
·				APPLICANT Lizhong Sun, et al.						
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.